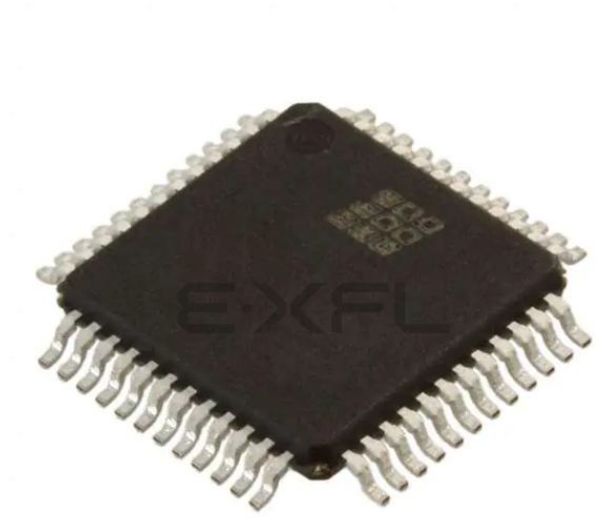
Lattice Semiconductor Corporation - LA4032ZC-75TN48E Datasheet



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Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Active
Programmable Type	In System Programmable
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	1.7V ~ 1.9V
Number of Logic Elements/Blocks	-
Number of Macrocells	32
Number of Gates	-
Number of I/O	32
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	48-TQFP
Supplier Device Package	48-TQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/la4032zc-75tn48e

Table 2. LA-ispMACH 4000Z Automotive Family Selection Guide

	LA-ispMACH 4032Z	LA-ispMACH 4064Z	LA-ispMACH 4128Z
Macrocells	32	64	128
I/O + Dedicated Inputs	32+4	32+4/64+10	64+10
t_{PD} (ns)	7.5	7.5	7.5
t_S (ns)	4.5	4.5	4.5
t_{CO} (ns)	4.5	4.5	4.5
f_{MAX} (MHz)	168	168	168
Supply Voltage (V)	1.8V	1.8V	1.8V
Pins/Package	48-pin Lead-Free TQFP	48-pin Lead-Free TQFP 100-pin Lead-Free TQFP	100-pin Lead-Free TQFP

The LA-ispMACH 4000V/Z automotive family offers densities ranging from 32 to 128 macrocells. There are multiple density-I/O combinations in Thin Quad Flat Pack (TQFP) packages ranging from 44 to 144 pins. Tables 1 and 2 show the macrocell, package and I/O options, along with other key parameters.

The LA-ispMACH 4000V/Z automotive family has enhanced system integration capabilities. It supports 3.3V (4000V and 1.8V (4000Z) supply voltages and 3.3V, 2.5V and 1.8V interface voltages. Additionally, inputs can be safely driven up to 5.5V when an I/O bank is configured for 3.3V operation, making this family 5V tolerant. The LA-ispMACH 4000V/Z also offers enhanced I/O features such as slew rate control, PCI compatibility, bus-keeper latches, pull-up resistors, pull-down resistors, open drain outputs and hot socketing. The LA-ispMACH 4000V/Z automotive family is in-system programmable through the IEEE Standard 1532 interface. IEEE Standard 1149.1 boundary scan testing capability also allows product testing on automated test equipment. The 1532 interface signals TCK, TMS, TDI and TDO are referenced to VCC (logic core).

Overview

The LA-ispMACH 4000V/Z automotive devices consist of multiple 36-input, 16-macrocell Generic Logic Blocks (GLBs) interconnected by a Global Routing Pool (GRP). Output Routing Pools (ORPs) connect the GLBs to the I/O Blocks (IOBs), which contain multiple I/O cells. This architecture is shown in Figure 1.

Figure 1. Functional Block Diagram

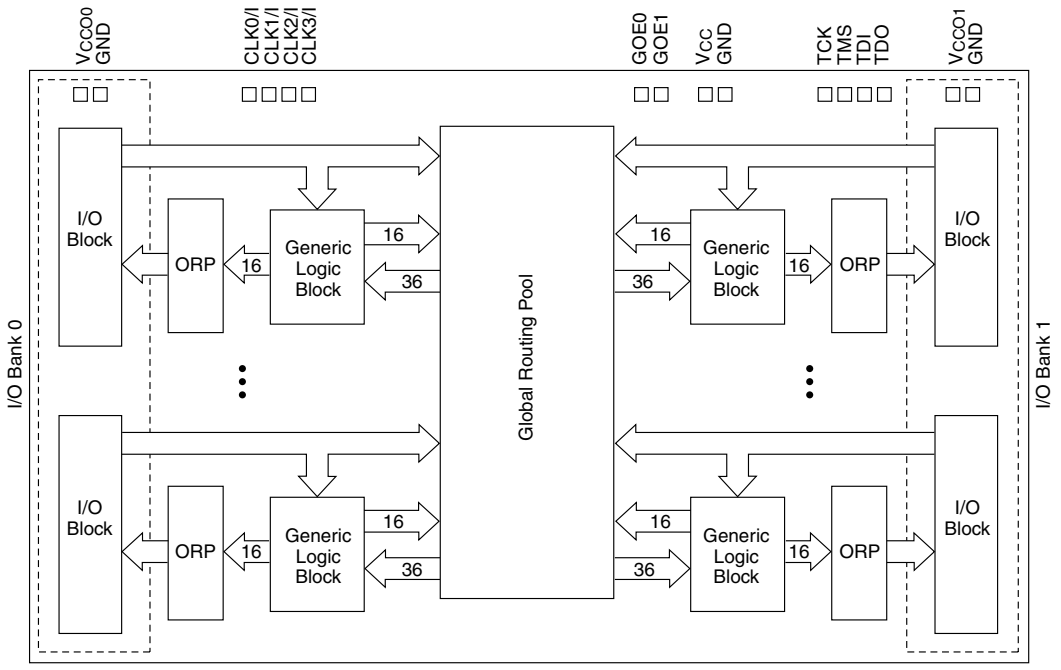


Table 5. Product Term Expansion Capability

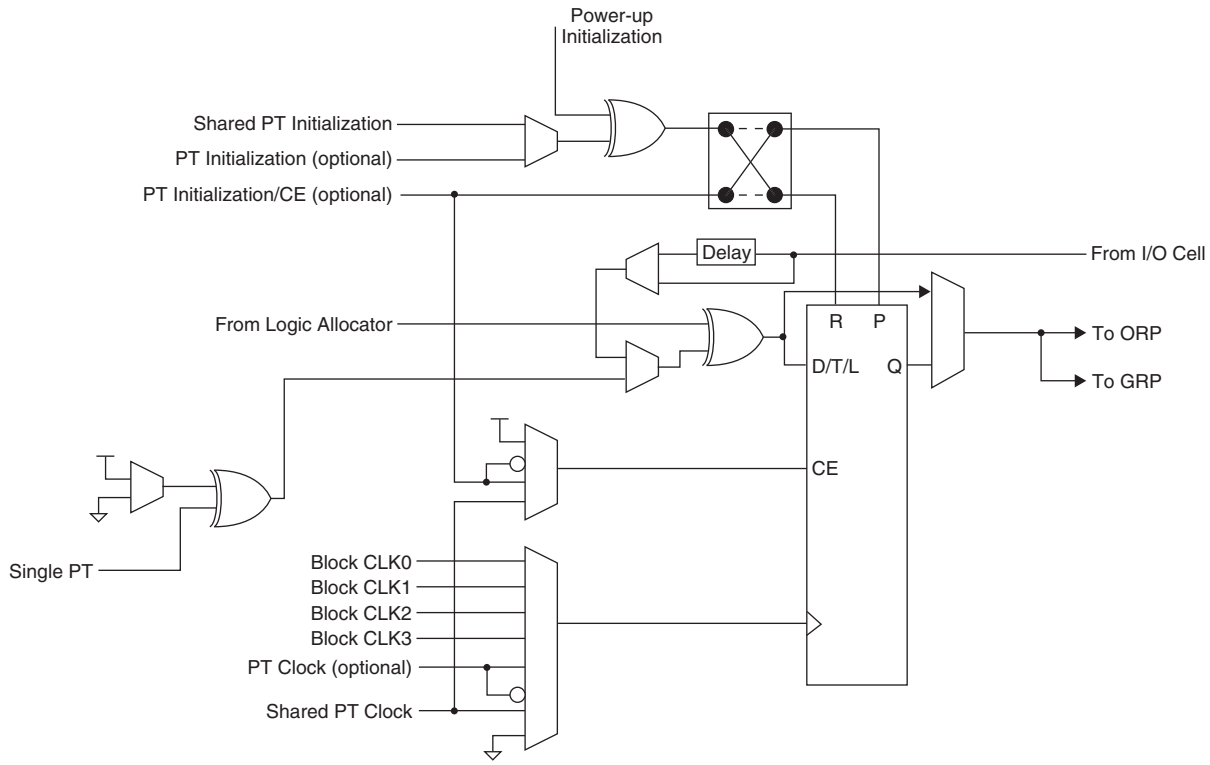
Expansion Chains	Macrocells Associated with Expansion Chain (with Wrap Around)	Max PT/Macrocell
Chain-0	M0 → M4 → M8 → M12 → M0	75
Chain-1	M1 → M5 → M9 → M13 → M1	80
Chain-2	M2 → M6 → M10 → M14 → M2	75
Chain-3	M3 → M7 → M11 → M15 → M3	70

Every time the super cluster allocator is used, there is an incremental delay of t_{EXP}. When the super cluster allocator is used, all destinations other than the one being steered to, are given the value of ground (i.e., if the super cluster is steered to M (n+4), then M (n) is ground).

Macrocell

The 16 macrocells in the GLB are driven by the 16 outputs from the logic allocator. Each macrocell contains a programmable XOR gate, a programmable register/latch, along with routing for the logic and control functions. Figure 5 shows a graphical representation of the macrocell. The macrocells feed the ORP and GRP. A direct input from the I/O cell allows designers to use the macrocell to construct high-speed input registers. A programmable delay in this path allows designers to choose between the fastest possible set-up time and zero hold time.

Figure 5. Macrocell



Enhanced Clock Multiplexer

The clock input to the flip-flop can select any of the four block clocks along with the shared PT clock, and true and complement forms of the optional individual term clock. An 8:1 multiplexer structure is used to select the clock. The eight sources for the clock multiplexer are as follows:

- Block CLK0
- Block CLK1
- Block CLK2

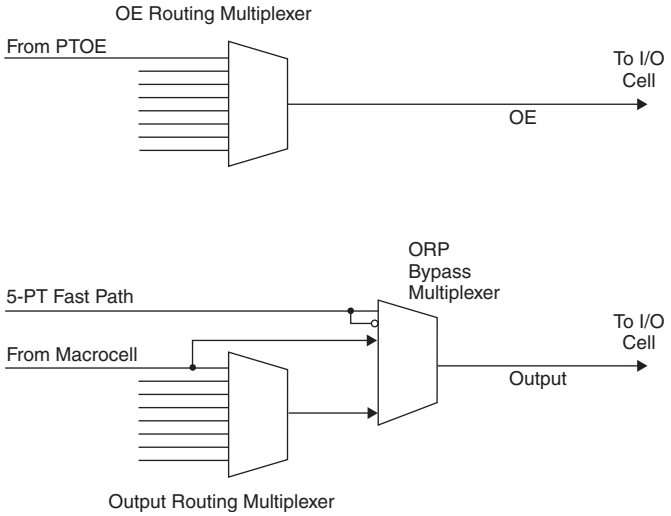
Output Routing Pool (ORP)

The Output Routing Pool allows macrocell outputs to be connected to any of several I/O cells within an I/O block. This provides greater flexibility in determining the pinout and allows design changes to occur without affecting the pinout. The output routing pool also provides a parallel capability for routing macrocell-level OE product terms. This allows the OE product term to follow the macrocell output as it is switched between I/O cells. Additionally, the output routing pool allows the macrocell output or true and complement forms of the 5-PT bypass signal to bypass the output routing multiplexers and feed the I/O cell directly. The enhanced ORP of the LA-ispMACH 4000V/Z family consists of the following elements:

- Output Routing Multiplexers
- OE Routing Multiplexers
- Output Routing Pool Bypass Multiplexers

Figure 7 shows the structure of the ORP from the I/O cell perspective. This is referred to as an ORP slice. Each ORP has as many ORP slices as there are I/O cells in the corresponding I/O block.

Figure 7. ORP Slice



Output Routing Multiplexers

The details of connections between the macrocells and the I/O cells vary across devices and within a device dependent on the maximum number of I/Os available. Tables 6-10 provide the connection details.

Table 6. ORP Combinations for I/O Blocks with 8 I/Os

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M2, M3, M4, M5, M6, M7, M8, M9
I/O 2	M4, M5, M6, M7, M8, M9, M10, M11
I/O 3	M6, M7, M8, M9, M10, M11, M12, M13
I/O 4	M8, M9, M10, M11, M12, M13, M14, M15
I/O 5	M10, M11, M12, M13, M14, M15, M0, M1
I/O 6	M12, M13, M14, M15, M0, M1, M2, M3
I/O 7	M14, M15, M0, M1, M2, M3, M4, M5

Figure 9. Global OE Generation for All Devices Except LA-ispMACH 4032V/Z

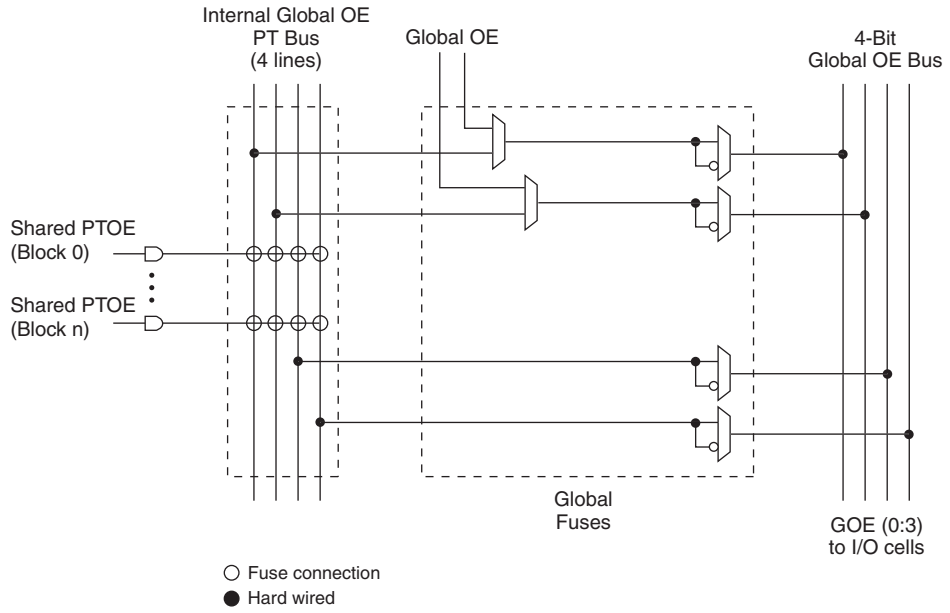
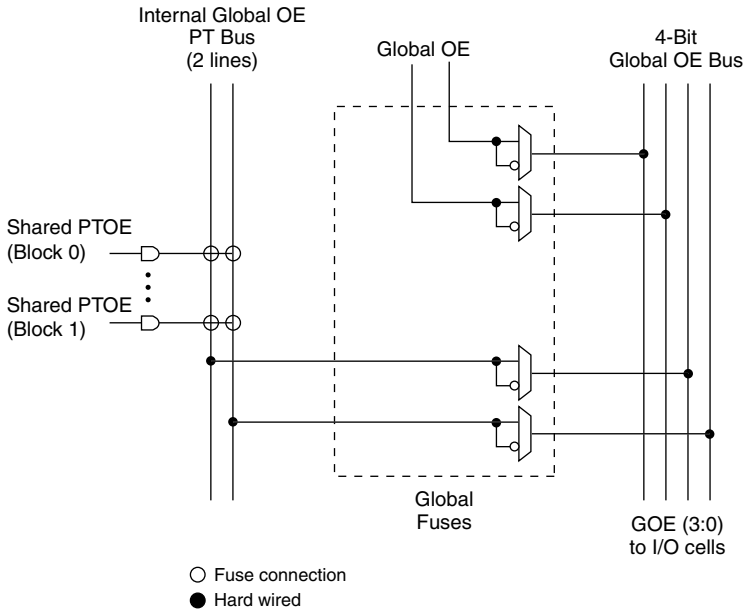


Figure 10. Global OE Generation for LA-ispMACH 4032V/Z



Zero Power/Low Power and Power Management

The LA-ispMACH 4000V/Z automotive family is designed with high speed low power design techniques to offer both high speed and low power. With an advanced E^2 low power cell and non sense-amplifier design approach (full CMOS logic approach), the LA-ispMACH 4000V/Z automotive family offers SuperFAST pin-to-pin speeds, while simultaneously delivering low standby power without needing any “turbo bits” or other power management schemes associated with a traditional sense-amplifier approach.

The zero power LA-ispMACH 4000Z is based on the 1.8V ispMACH 4000C family. With innovative circuit design changes, the LA-ispMACH 4000Z family is able to achieve the industry's "lowest static power".

IEEE 1149.1-Compliant Boundary Scan Testability

All LA-ispMACH 4000V/Z automotive devices have boundary scan cells and are compliant to the IEEE 1149.1 standard. This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic notes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test node data to be captured and shifted out for verification. In addition, these devices can be linked into a board-level serial scan path for more board-level testing. The test access port operates with an LVCMOS interface that corresponds to the power supply voltage.

I/O Quick Configuration

To facilitate the most efficient board test, the physical nature of the I/O cells must be set before running any continuity tests. As these tests are fast, by nature, the overhead and time that is required for configuration of the I/Os' physical nature should be minimal so that board test time is minimized. The LA-ispMACH 4000V/Z automotive family of devices allows this by offering the user the ability to quickly configure the physical nature of the I/O cells. This quick configuration takes milliseconds to complete, whereas it takes seconds for the entire device to be programmed. Lattice's ispVM™ System programming software can either perform the quick configuration through the PC parallel port, or can generate the ATE or test vectors necessary for a third-party test system.

IEEE 1532-Compliant In-System Programming

Programming devices in-system provides a number of significant benefits including: rapid prototyping, lower inventory levels, higher quality and the ability to make in-field modifications. The LA-ispMACH 4000V/Z automotive devices provide In-System Programming (ISP™) capability through the Boundary Scan Test Access Port. This capability has been implemented in a manner that ensures that the port remains complaint to the IEEE 1149.1 standard. By using IEEE 1149.1 as the communication interface through which ISP is achieved, users get the benefit of a standard, well-defined interface. All LA-ispMACH 4000V/Z automotive devices are also compliant with the IEEE 1532 standard.

The LA-ispMACH 4000V/Z automotive devices can be programmed across the commercial temperature and voltage range. The PC-based Lattice software facilitates in-system programming of LA-ispMACH 4000V/Z automotive devices. The software takes the JEDEC file output produced by the design implementation software, along with information about the scan chain, and creates a set of vectors used to drive the scan chain. The software can use these vectors to drive a scan chain via the parallel port of a PC. Alternatively, the software can output files in formats understood by common automated test equipment. This equipment can then be used to program LA-ispMACH 4000V/Z automotive devices during the testing of a circuit board.

User Electronic Signature

The User Electronic Signature (UES) allows the designer to include identification bits or serial numbers inside the device, stored in E^2CMOS memory. The LA-ispMACH 4000V/Z automotive device contains 32 UES bits that can be configured by the user to store unique data such as ID codes, revision numbers or inventory control codes.

Security Bit

A programmable security bit is provided on the LA-ispMACH 4000V/Z automotive devices as a deterrent to unauthorized copying of the array configuration patterns. Once programmed, this bit defeats readback of the programmed pattern by a device programmer, securing proprietary designs from competitors. Programming and verification are also defeated by the security bit. The bit can only be reset by erasing the entire device.

Hot Socketing

The LA-ispMACH 4000V/Z automotive devices are well-suited for applications that require hot socketing capability. Hot socketing a device requires that the device, during power-up and down, can tolerate active signals on the I/Os

and inputs without being damaged. Additionally, it requires that the effects of I/O pin loading be minimal on active signals. The LA-ispMACH 4000V/Z automotive devices provide this capability for input voltages in the range 0V to 3.0V.

Density Migration

The LA-ispMACH 4000V/Z automotive family has been designed to ensure that different density devices in the same package have the same pin-out. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is possible to shift a lower utilization design targeted for a high density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

AEC-Q100 Tested and Qualified

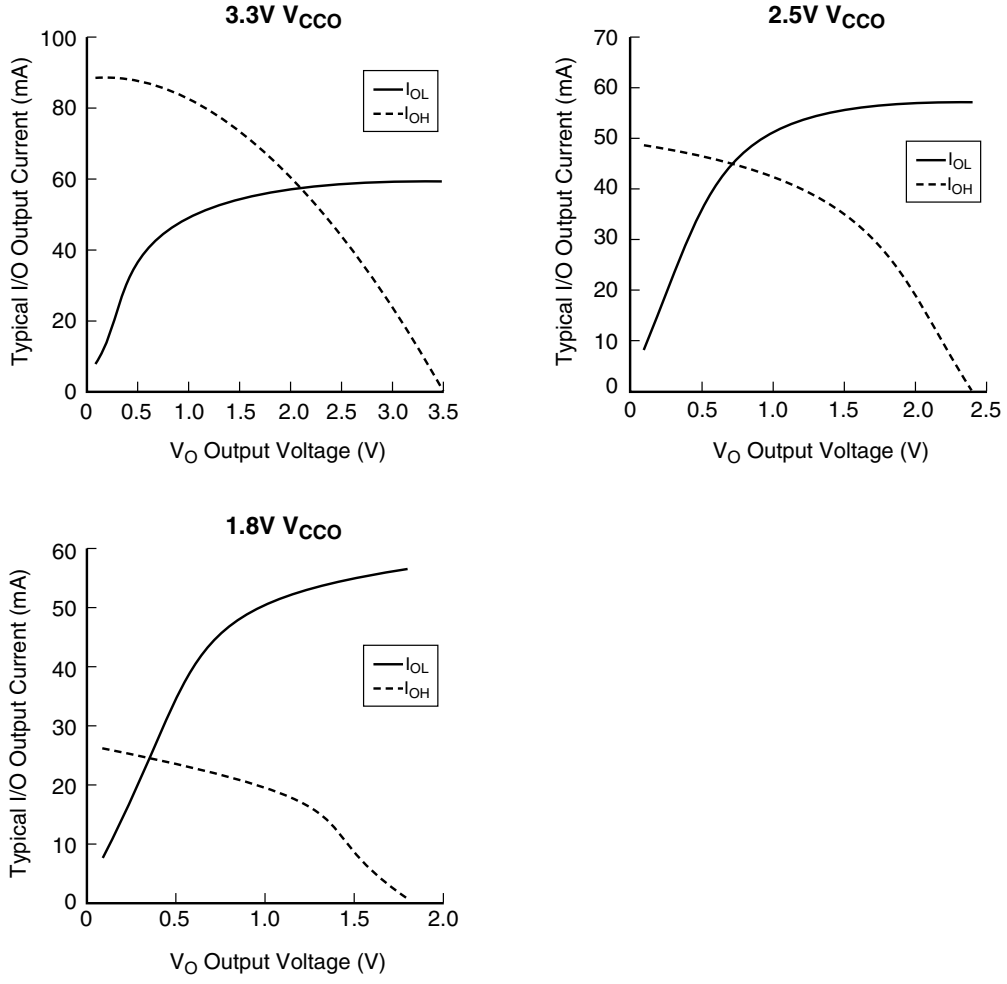
The Automotive Electronics Council (AEC) consists of two committees: the Quality Systems Committee and the Component Technical Committee. These committees are composed of representatives from sustaining and other associate members. The AEC Component Technical Committee is the standardization body for establishing standards for reliable, high quality electronic components. In particular, the AEC-Q100 specification “Stress Test for Qualification for Integrated Circuits” defines qualification and re-qualification requirements for electronic components. Components meeting these specifications are suitable for use in the harsh automotive environment without additional component-level qualification testing. Lattice's LA-ispMACH 4000V/Z and LA-MachXO devices completed and passed the requirements of the AEC-Q100 specification.

I/O DC Electrical Characteristics

Over Recommended Operating Conditions

Standard	V_{IL}		V_{IH}		V_{OL} Max (V)	V_{OH} Min (V)	I_{OL}[1] (mA)	I_{OH}[1] (mA)
	Min (V)	Max (V)	Min (V)	Max (V)				
LVTTL	-0.3	0.80	2.0	5.5	0.40	V_{CCO} - 0.40	8.0	-4.0
					0.20	V_{CCO} - 0.20	0.1	-0.1
LVCMOS 3.3	-0.3	0.80	2.0	5.5	0.40	V_{CCO} - 0.40	8.0	-4.0
					0.20	V_{CCO} - 0.20	0.1	-0.1
LVCMOS 2.5	-0.3	0.70	1.70	3.6	0.40	V_{CCO} - 0.40	8.0	-4.0
					0.20	V_{CCO} - 0.20	0.1	-0.1
LVCMOS 1.8 (4000V)	-0.3	0.63	1.17	3.6	0.40	V_{CCO} - 0.45	2.0	-2.0
					0.20	V_{CCO} - 0.20	0.1	-0.1
LVCMOS 1.8 (4000Z)	-0.3	0.35 * V_{CC}	0.65 * V_{CC}	3.6	0.40	V_{CCO} - 0.45	2.0	-2.0
					0.20	V_{CCO} - 0.20	0.1	-0.1
PCI 3.3 (4000V)	-0.3	1.08	1.5	5.5	0.1 V_{CCO}	0.9 V_{CCO}	1.5	-0.5
PCI 3.3 (4000Z)	-0.3	0.3 * 3.3 * (V_{CC} / 1.8)	0.5 * 3.3 * (V_{CC} / 1.8)	5.5	0.1 V_{CCO}	0.9 V_{CCO}	1.5	-0.5

1. The average DC current drawn by I/Os between adjacent bank GND connections, or between the last GND in an I/O bank and the end of the I/O bank, as shown in the logic signals connection table, shall not exceed *n**8mA. Where *n* is the number of I/Os between bank GND connections or between the last GND in a bank and the end of a bank.



LA-ispMACH 4000V/Z External Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description[1, 2, 3]	LA-ispMACH 4000V -75		LA-ispMACH 4000Z -75		Units
		Min.	Max.	Min.	Max.	
t_{PD}	5-PT bypass combinatorial propagation delay	—	7.5	—	7.5	ns
t_{PD_MC}	20-PT combinatorial propagation delay through macrocell	—	8.0	—	8.0	ns
t_S	GLB register setup time before clock	4.5	—	4.5	—	ns
t_{ST}	GLB register setup time before clock with T-type register	4.7	—	4.7	—	ns
t_{SIR}	GLB register setup time before clock, input register path	1.7	—	1.4	—	ns
t_{SIRZ}	GLB register setup time before clock with zero hold	2.7	—	2.7	—	ns
t_H	GLB register hold time after clock	0.0	—	0.0	—	ns
t_{HT}	GLB register hold time after clock with T-type register	0.0	—	0.0	—	ns
t_{HIR}	GLB register hold time after clock, input register path	1.0	—	1.3	—	ns
t_{HIRZ}	GLB register hold time after clock, input register path with zero hold	0.0	—	0.0	—	ns
t_{CO}	GLB register clock-to-output delay	—	4.5	—	4.5	ns
t_R	External reset pin to output delay	—	9.0	—	9.0	ns
t_{RW}	External reset pulse duration	4.0	—	4.0	—	ns
$t_{PTOE/DIS}$	Input to output local product term output enable/disable	—	9.0	—	9.0	ns
$t_{GPTOE/DIS}$	Input to output global product term output enable/disable	—	10.3	—	10.5	ns
$t_{GOE/DIS}$	Global OE input to output enable/disable	—	7.0	—	7.0	ns
t_{CW}	Global clock width, high or low	2.8	—	2.8	—	ns
t_{GW}	Global gate width low (for low transparent) or high (for high transparent)	2.8	—	2.8	—	ns
t_{WIR}	Input register clock width, high or low	2.8	—	2.8	—	ns
f_{MAX}[4]	Clock frequency with internal feedback	—	168	—	168	MHz
f_{MAX} (Ext.)	Clock frequency with external feedback, [1/ (t_S + t_{CO})]	—	111	—	111	MHz

1. Timing numbers are based on default LVCMOS 1.8 I/O buffers. Use timing adjusters provided to calculate other standards.
2. Measured using standard switching circuit, assuming GRP loading of 1 and 1 output switching.
3. Pulse widths and clock widths less than minimum will cause unknown behavior.
4. Standard 16-bit counter using GRP feedback.

Timing v.3.2

LA-ispMACH 4000V/Z Timing Adders[1]

Adder Type	Base Parameter	Description	LA-ispMACH 4000V -75		LA-ispMACH 4000Z -75		Units
			Min.	Max.	Min.	Max.	
Optional Delay Adders							
t_{INDIO}	t_{INREG}	Input register delay	—	1.00	—	1.30	ns
t_{EXP}	t_{MCELL}	Product term expander delay	—	0.33	—	0.50	ns
t_{ORP}	—	Output routing pool delay	—	0.05	—	0.40	ns
t_{BLA}	t_{ROUTE}	Additional block loading adder	—	0.05	—	0.05	ns
t_{IOI} Input Adjusters							
LVTTL_in	t_{IN}, t_{GCLK_IN}, t_{GOE}	Using LVTTL standard	—	0.60	—	0.60	ns
LVCMOS33_in	t_{IN}, t_{GCLK_IN}, t_{GOE}	Using LVCMOS 3.3 standard	—	0.60	—	0.60	ns
LVCMOS25_in	t_{IN}, t_{GCLK_IN}, t_{GOE}	Using LVCMOS 2.5 standard	—	0.60	—	0.60	ns
LVCMOS18_in	t_{IN}, t_{GCLK_IN}, t_{GOE}	Using LVCMOS 1.8 standard	—	0.00	—	0.00	ns
PCI_in	t_{IN}, t_{GCLK_IN}, t_{GOE}	Using PCI compatible input	—	0.60	—	0.60	ns
t_{IOO} Output Adjusters							
LVTTL_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as TTL buffer	—	0.20	—	0.20	ns
LVCMOS33_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 3.3V buffer	—	0.20	—	0.20	ns
LVCMOS25_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 2.5V buffer	—	0.10	—	0.10	ns
LVCMOS18_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 1.8V buffer	—	0.00	—	0.00	ns
PCI_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as PCI compatible buffer	—	0.20	—	0.20	ns
Slow Slew	t_{BUF}, t_{EN}	Output configured for slow slew rate	—	1.00	—	1.00	ns

Note: Open drain timing is the same as corresponding LVCMOS timing.

Timing v.3.2

1. Refer to TN1004, ispMACH 4000 Timing Model Design and Usage Guidelines for information regarding use of these adders.

Switching Test Conditions

Figure 12 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Table 9.

Figure 12. Output Test Load, LVTTL and LVCMOS Standards

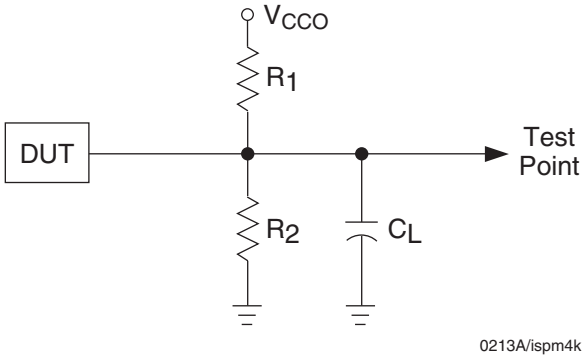


Table 9. Test Fixture Required Components

Test Condition	R_1	R_2	C_L[1]	Timing Ref.	V_{CCO}
LVCMOS I/O, (L -> H, H -> L)	106Ω	106Ω	35pF	LVCMOS 3.3 = 1.5V	LVCMOS 3.3 = 3.0V
				LVCMOS 2.5 = V_{CCO}/2	LVCMOS 2.5 = 2.3V
				LVCMOS 1.8 = V_{CCO}/2	LVCMOS 1.8 = 1.65V
LVCMOS I/O (Z -> H)	∞	106Ω	35pF	1.5V	3.0V
LVCMOS I/O (Z -> L)	106Ω	∞	35pF	1.5V	3.0V
LVCMOS I/O (H -> Z)	∞	106Ω	5pF	V_{OH} - 0.3	3.0V
LVCMOS I/O (L -> Z)	106Ω	∞	5pF	V_{OL} + 0.3	3.0V

1. C_L includes test fixtures and probe capacitance.

LA-ispMACH 4032V and 4064V Logic Signal Connections: 44-Pin TQFP

Pin Number	Bank Number	LA-ispMACH 4032V		LA-ispMACH 4064V	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
1	-	TDI	-	TDI	-
2	0	A5	A^5	A10	A^5
3	0	A6	A^6	A12	A^6
4	0	A7	A^7	A14	A^7
5	0	GND (Bank 0)	-	GND (Bank 0)	-
6	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-
7	0	A8	A^8	B0	B^0
8	0	A9	A^9	B2	B^1
9	0	A10	A^10	B4	B^2
10	-	TCK	-	TCK	-
11	-	VCC	-	VCC	-
12	-	GND	-	GND	-
13	0	A12	A^12	B8	B^4
14	0	A13	A^13	B10	B^5
15	0	A14	A^14	B12	B^6
16	0	A15	A^15	B14	B^7
17	1	CLK2/I	-	CLK2/I	-
18	1	B0	B^0	C0	C^0
19	1	B1	B^1	C2	C^1
20	1	B2	B^2	C4	C^2
21	1	B3	B^3	C6	C^3
22	1	B4	B^4	C8	C^4
23	-	TMS	-	TMS	-
24	1	B5	B^5	C10	C^5
25	1	B6	B^6	C12	C^6
26	1	B7	B^7	C14	C^7
27	1	GND (Bank 1)	-	GND (Bank 1)	-
28	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-
29	1	B8	B^8	D0	D^0
30	1	B9	B^9	D2	D^1
31	1	B10	B^10	D4	D^2
32	-	TDO	-	TDO	-
33	-	VCC	-	VCC	-
34	-	GND	-	GND	-
35	1	B12	B^12	D8	D^4
36	1	B13	B^13	D10	D^5
37	1	B14	B^14	D12	D^6
38	1	B15/GOE1	B^15	D14/GOE1	D^7
39	0	CLK0/I	-	CLK0/I	-
40	0	A0/GOE0	A^0	A0/GOE0	A^0
41	0	A1	A^1	A2	A^1
42	0	A2	A^2	A4	A^2

LA-ispMACH 4032V and 4064V Logic Signal Connections: 44-Pin TQFP

Pin Number	Bank Number	LA-ispMACH 4032V		LA-ispMACH 4064V	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
43	0	A3	A^3	A6	A^3
44	0	A4	A^4	A8	A^4

LA-ispMACH 4032V/Z and 4064V/Z Logic Signal Connections: 48-Pin TQFP

Pin Number	Bank Number	LA-ispMACH 4032V/Z		LA-ispMACH 4064V/Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
1	-	TDI	-	TDI	-
2	0	A5	A^5	A10	A^5
3	0	A6	A^6	A12	A^6
4	0	A7	A^7	A14	A^7
5	0	GND (Bank 0)	-	GND (Bank 0)	-
6	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-
7	0	A8	A^8	B0	B^0
8	0	A9	A^9	B2	B^1
9	0	A10	A^10	B4	B^2
10	0	A11	A^11	B6	B^3
11	-	TCK	-	TCK	-
12	-	VCC	-	VCC	-
13	-	GND	-	GND	-
14	0	A12	A^12	B8	B^4
15	0	A13	A^13	B10	B^5
16	0	A14	A^14	B12	B^6
17	0	A15	A^15	B14	B^7
18	0	CLK1/I	-	CLK1/I	-
19	1	CLK2/I	-	CLK2/I	-
20	1	B0	B^0	C0	C^0
21	1	B1	B^1	C2	C^1
22	1	B2	B^2	C4	C^2
23	1	B3	B^3	C6	C^3
24	1	B4	B^4	C8	C^4
25	-	TMS	-	TMS	-
26	1	B5	B^5	C10	C^5
27	1	B6	B^6	C12	C^6
28	1	B7	B^7	C14	C^7
29	1	GND (Bank 1)	-	GND (Bank 1)	-
30	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-
31	1	B8	B^8	D0	D^0
32	1	B9	B^9	D2	D^1
33	1	B10	B^10	D4	D^2
34	1	B11	B^11	D6	D^3
35	-	TDO	-	TDO	-

LA-ispMACH 4032V/Z and 4064V/Z Logic Signal Connections: 48-Pin TQFP

Pin Number	Bank Number	LA-ispMACH 4032V/Z		LA-ispMACH 4064V/Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
36	-	VCC	-	VCC	-
37	-	GND	-	GND	-
38	1	B12	B^12	D8	D^4
39	1	B13	B^13	D10	D^5
40	1	B14	B^14	D12	D^6
41	1	B15/GOE1	B^15	D14/GOE1	D^7
42	1	CLK3/I	-	CLK3/I	-
43	0	CLK0/I	-	CLK0/I	-
44	0	A0/GOE0	A^0	A0/GOE0	A^0
45	0	A1	A^1	A2	A^1
46	0	A2	A^2	A4	A^2
47	0	A3	A^3	A6	A^3
48	0	A4	A^4	A8	A^4

LA-ispMACH 4064V/Z and 4128V/Z Logic Signal Connections: 100-Pin TQFP

Pin Number	Bank Number	LA-ispMACH 4064V/Z		LA-ispMACH 4128V/Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
1	-	GND	-	GND	-
2	-	TDI	-	TDI	-
3	0	A8	A^8	B0	B^0
4	0	A9	A^9	B2	B^1
5	0	A10	A^10	B4	B^2
6	0	A11	A^11	B6	B^3
7	0	GND (Bank 0)	-	GND (Bank 0)	-
8	0	A12	A^12	B8	B^4
9	0	A13	A^13	B10	B^5
10	0	A14	A^14	B12	B^6
11	0	A15	A^15	B13	B^7
12*	0	I	-	I	-
13	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-
14	0	B15	B^15	C14	C^7
15	0	B14	B^14	C12	C^6
16	0	B13	B^13	C10	C^5
17	0	B12	B^12	C8	C^4
18	0	GND (Bank 0)	-	GND (Bank 0)	-
19	0	B11	B^11	C6	C^3
20	0	B10	B^10	C5	C^2
21	0	B9	B^9	C4	C^1
22	0	B8	B^8	C2	C^0
23*	0	I	-	I	-
24	-	TCK	-	TCK	-

LA-ispMACH 4064V/Z and 4128V/Z Logic Signal Connections: 100-Pin TQFP

Pin Number	Bank Number	LA-ispMACH 4064V/Z		LA-ispMACH 4128V/Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
25	-	VCC	-	VCC	-
26	-	GND	-	GND	-
27*	0	I	-	I	-
28	0	B7	B^7	D13	D^7
29	0	B6	B^6	D12	D^6
30	0	B5	B^5	D10	D^5
31	0	B4	B^4	D8	D^4
32	0	GND (Bank 0)	-	GND (Bank 0)	-
33	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-
34	0	B3	B^3	D6	D^3
35	0	B2	B^2	D4	D^2
36	0	B1	B^1	D2	D^1
37	0	B0	B^0	D0	D^0
38	0	CLK1/I	-	CLK1/I	-
39	1	CLK2/I	-	CLK2/I	-
40	-	VCC	-	VCC	-
41	1	C0	C^0	E0	E^0
42	1	C1	C^1	E2	E^1
43	1	C2	C^2	E4	E^2
44	1	C3	C^3	E6	E^3
45	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-
46	1	GND (Bank 1)	-	GND (Bank 1)	-
47	1	C4	C^4	E8	E^4
48	1	C5	C^5	E10	E^5
49	1	C6	C^6	E12	E^6
50	1	C7	C^7	E14	E^7
51	-	GND	-	GND	-
52	-	TMS	-	TMS	-
53	1	C8	C^8	F0	F^0
54	1	C9	C^9	F2	F^1
55	1	C10	C^10	F4	F^2
56	1	C11	C^11	F6	F^3
57	1	GND (Bank 1)	-	GND (Bank 1)	-
58	1	C12	C^12	F8	F^4
59	1	C13	C^13	F10	F^5
60	1	C14	C^14	F12	F^6
61	1	C15	C^15	F13	F^7
62*	1	I	-	I	-
63	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-
64	1	D15	D^15	G14	G^7
65	1	D14	D^14	G12	G^6
66	1	D13	D^13	G10	G^5
67	1	D12	D^12	G8	G^4

LA-ispMACH 4128V Logic Signal Connections: 128-Pin TQFP

Pin Number	Bank Number	LA-ispMACH 4128V	
		GLB/MC/Pad	ORP
1	0	GND	-
2	0	TDI	-
3	0	VCCO (Bank 0)	-
4	0	B0	B^0
5	0	B1	B^1
6	0	B2	B^2
7	0	B4	B^3
8	0	B5	B^4
9	0	B6	B^5
10	0	GND (Bank 0)	-
11	0	B8	B^6
12	0	B9	B^7
13	0	B10	B^8
14	0	B12	B^9
15	0	B13	B^10
16	0	B14	B^11
17	0	VCCO (Bank 0)	-
18	0	C14	C^11
19	0	C13	C^10
20	0	C12	C^9
21	0	C10	C^8
22	0	C9	C^7
23	0	C8	C^6
24	0	GND (Bank 0)	-
25	0	C6	C^5
26	0	C5	C^4
27	0	C4	C^3
28	0	C2	C^2
29	0	C0	C^0
30	0	VCCO (Bank 0)	-
31	0	TCK	-
32	0	VCC	-
33	0	GND	-
34	0	D14	D^11
35	0	D13	D^10
36	0	D12	D^9
37	0	D10	D^8
38	0	D9	D^7
39	0	D8	D^6
40	0	GND (Bank 0)	-
41	0	VCCO (Bank 0)	-
42	0	D6	D^5

LA-ispMACH 4128V Logic Signal Connections: 128-Pin TQFP (Cont.)

Pin Number	Bank Number	LA-ispMACH 4128V	
		GLB/MC/Pad	ORP
43	0	D5	D^4
44	0	D4	D^3
45	0	D2	D^2
46	0	D1	D^1
47	0	D0	D^0
48	0	CLK1/I	-
49	1	GND (Bank 1)	-
50	1	CLK2/I	-
51	1	VCC	-
52	1	E0	E^0
53	1	E1	E^1
54	1	E2	E^2
55	1	E4	E^3
56	1	E5	E^4
57	1	E6	E^5
58	1	VCCO (Bank 1)	-
59	1	GND (Bank 1)	-
60	1	E8	E^6
61	1	E9	E^7
62	1	E10	E^8
63	1	E12	E^9
64	1	E14	E^11
65	1	GND	-
66	1	TMS	-
67	1	VCCO (Bank 1)	-
68	1	F0	F^0
69	1	F1	F^1
70	1	F2	F^2
71	1	F4	F^3
72	1	F5	F^4
73	1	F6	F^5
74	1	GND (Bank 1)	-
75	1	F8	F^6
76	1	F9	F^7
77	1	F10	F^8
78	1	F12	F^9
79	1	F13	F^10
80	1	F14	F^11
81	1	VCCO (Bank 1)	-
82	1	G14	G^11
83	1	G13	G^10
84	1	G12	G^9
85	1	G10	G^8

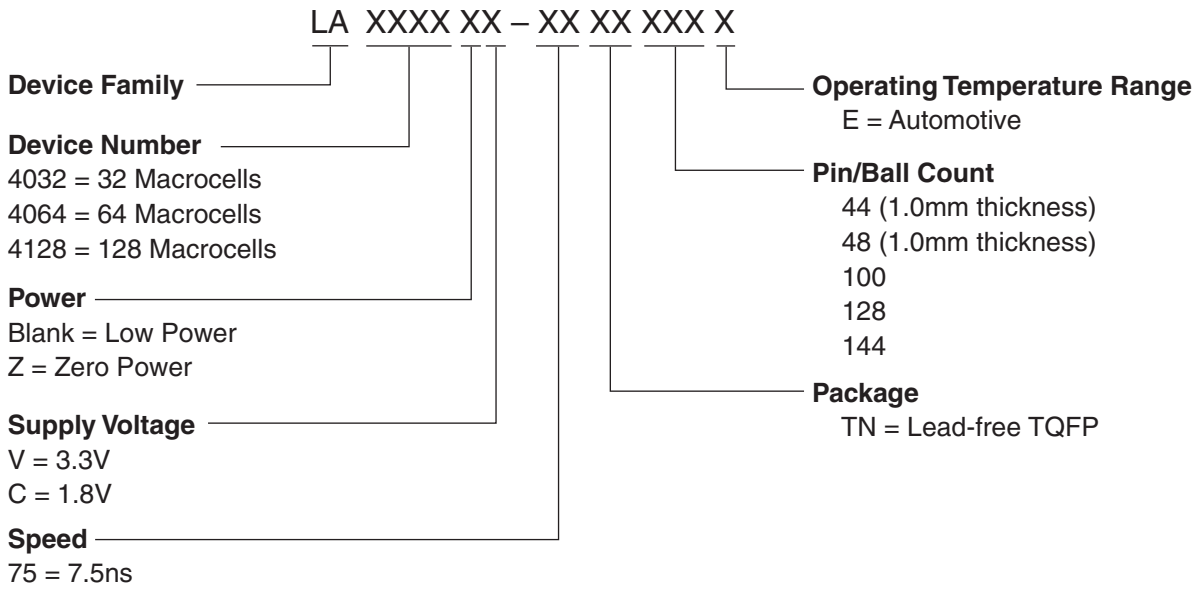
LA-ispMACH 4128V Logic Signal Connections: 128-Pin TQFP (Cont.)

Pin Number	Bank Number	LA-ispMACH 4128V	
		GLB/MC/Pad	ORP
86	1	G9	G^7
87	1	G8	G^6
88	1	GND (Bank 1)	-
89	1	G6	G^5
90	1	G5	G^4
91	1	G4	G^3
92	1	G2	G^2
93	1	G0	G^0
94	1	VCCO (Bank 1)	-
95	1	TDO	-
96	1	VCC	-
97	1	GND	-
98	1	H14	H^11
99	1	H13	H^10
100	1	H12	H^9
101	1	H10	H^8
102	1	H9	H^7
103	1	H8	H^6
104	1	GND (Bank 1)	-
105	1	VCCO (Bank 1)	-
106	1	H6	H^5
107	1	H5	H^4
108	1	H4	H^3
109	1	H2	H^2
110	1	H1	H^1
111	1	H0/GOE1	H^0
112	1	CLK3/I	-
113	0	GND (Bank 0)	-
114	0	CLK0/I	-
115	0	VCC	-
116	0	A0/GOE0	A^0
117	0	A1	A^1
118	0	A2	A^2
119	0	A4	A^3
120	0	A5	A^4
121	0	A6	A^5
122	0	VCCO (Bank 0)	-
123	0	GND (Bank 0)	-
124	0	A8	A^6
125	0	A9	A^7
126	0	A10	A^8
127	0	A12	A^9
128	0	A14	A^11

LA-ispMACH 4128V Logic Signal Connections: 144-Pin TQFP

Pin Number	Bank Number	LA-ispMACH 4128V	
		GLB/MC/Pad	ORP
1	-	GND	-
2	-	TDI	-
3	0	VCCO (Bank 0)	-
4	0	B0	B^0
5	0	B1	B^1
6	0	B2	B^2
7	0	B4	B^3
8	0	B5	B^4
9	0	B6	B^5
10	0	GND (Bank 0)	-
11	0	B8	B^6
12	0	B9	B^7
13	0	B10	B^8
14	0	B12	B^9
15	0	B13	B^10
16	0	B14	B^11
17	-	NC	-
18	0	GND (Bank 0)[1]	-
19	0	VCCO (Bank 0)	-
20	0	NC	-
21	0	C14	C^11
22	0	C13	C^10
23	0	C12	C^9
24	0	C10	C^8
25	0	C9	C^7
26	0	C8	C^6
27	0	GND (Bank 0)	-
28	0	C6	C^5
29	0	C5	C^4
30	0	C4	C^3
31	0	C2	C^2
32	0	C1	C^1
33	0	C0	C^0
34	0	VCCO (Bank 0)	-
35	-	TCK	-
36	-	VCC	-
37	-	GND	-
38	0	NC	-
39	0	D14	D^11
40	0	D13	D^10
41	0	D12	D^9
42	0	D10	D^8

Part Number Description



Ordering Information

Device	Part Number	Macrocells	Voltage	t_{PD}	Package	Pin/Ball Count	I/O	Grade
LA4032V	LA4032V-75TN48E	32	3.3	7.5	Lead-free TQFP	48	32	E
	LA4032V-75TN44E	32	3.3	7.5	Lead-free TQFP	44	30	E
LA4064V	LA4064V-75TN100E	64	3.3	7.5	Lead-free TQFP	100	64	E
	LA4064V-75TN48E	64	3.3	7.5	Lead-free TQFP	48	32	E
	LA4064V-75TN44E	64	3.3	7.5	Lead-free TQFP	44	30	E
LA4128V	LA4128V-75TN144E	128	3.3	7.5	Lead-free TQFP	144	96	E
	LA4128V-75TN128E	128	3.3	7.5	Lead-free TQFP	128	92	E
	LA4128V-75TN100E	128	3.3	7.5	Lead-free TQFP	100	64	E
LA4032Z	LA4032ZC-75TN48E	32	1.8	7.5	Lead-free TQFP	48	32	E
LA4064Z	LA4064ZC-75TN100E	64	1.8	7.5	Lead-free TQFP	100	64	E
	LA4064ZC-75TN48E	64	1.8	7.5	Lead-free TQFP	48	32	E
LA4128Z	LA4128ZC-75TN100E	128	1.8	7.5	Lead-free TQFP	100	64	E

Automotive Disclaimer

Products are not designed, intended or warranted to be fail-safe and are not designed, intended or warranted for use in applications related to the deployment of airbags. Further, products are not intended to be used, designed or warranted for use in applications that affect the control of the vehicle unless there is a fail-safe or redundancy feature and also a warning signal to the operator of the vehicle upon failure. Use of products in such applications is fully at the risk of the customer, subject to applicable laws and regulations governing limitations on product liability.

For Further Information

In addition to this data sheet, the following technical notes may be helpful when designing with the LA-ispMACH 4000V/Z automotive family:

- TN1004, ispMACH 4000 Timing Model Design and Usage Guidelines
- TN1005, Power Estimation in ispMACH 4000V/B/C/Z Devices

Revision History

Date	Version	Change Summary
April 2006	01.0	Initial release.
October 2006	02.0	Added LA-ispMACH 4000Z support information throughout.
March 2007	02.1	Updated ispMACH 4000 Introduction section.
		Updated Signal Descriptions table.
September 2007	02.2	DC Electrical Characteristics table, removed duplicate specifications.
July 2008	02.3	Lowered the maximum supply current at 85°C to match the commercial product values.
		Added automotive disclaimer.
May 2009	02.4	Correction to t_{CW}, tGW, t_{WIR} and f_{MAX} parameters in External Switching Characteristics table.
May 2009	02.5	Correction to t_{CW}, tGW and t_{WIR} parameters in External Switching Characteristics table.